EEPROM Solutions for tiny modules

Complete range of ultra-tiny WLCSP and DFN packages

Less than 1 mm² and only 0.3-mm thick, ST offers a complete range of ultra-tiny EEPROM devices in a wide variety of densities, ensuring flexibility in parameter management while being almost invisible on the global PCB footprint. Devices with an I²C interface can be reduced to a 5-pin DFN package or a 4-ball WLCSP. Able to fit in the tiniest space on any PCB and weighing less than 1 mg, these ultra-thin devices meet ultra-light objectives.

KEY FEATURES
• DFN8 Small plastic package
  • Body size: 2 x 3 mm
  • Thickness: 0.55 mm
  • Weight: 16 mg
• DFN5 Small plastic package
  • Available for I²C only
  • Body size: 1.4 x 1.7 mm
  • Thickness: 0.55 mm
  • Weight: 6 mg
• 4- and 8-ball WLCSP
  • Size: Only 0.76 mm² (128-Kbit I²C version in 4-ball WLCSP)
  • Thickness: 0.3 to 0.6 mm
  • Backside coating options
  • Weight: Less than 1 mg

KEY BENEFITS
• DFN8 and DFN5:
  • Small PCB footprint
  • Robust package, easy handling
• WLCSP:
  • Smallest footprint for reduced PCB size
  • Designed for ultra-thin modules
  • Lightest weight

KEY APPLICATIONS
• Headsets
• Hearing aids
• Wi-Fi and Bluetooth Low Energy modules
• Camera modules
• Wearables
• GPS
• Drones
• Any modules combining advanced digital cores with severe space constraints
# PRODUCT PORTFOLIO FOR TINY MODULES

<table>
<thead>
<tr>
<th>Packages</th>
<th>Serial interface</th>
<th>1 Kb</th>
<th>2 Kb</th>
<th>4 Kb</th>
<th>8 Kb</th>
<th>16 Kb</th>
<th>32 Kb</th>
<th>64 Kb</th>
<th>128 Kb</th>
<th>256 Kb</th>
<th>512 Kb</th>
<th>1 Mb</th>
<th>2 Mb</th>
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</thead>
<tbody>
<tr>
<td>4-ball WL CSP</td>
<td>PC only</td>
<td>0.53 mm²</td>
<td>0.63 mm²</td>
<td>0.76 mm²</td>
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<td>DFN5</td>
<td>PC only</td>
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<td>Pitch: 0.4 mm</td>
<td>Weight: 6 mg</td>
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<tr>
<td>8-ball WL CSP</td>
<td>PC</td>
<td>1.1 mm²</td>
<td>1.5 mm²</td>
<td>1.8 mm²</td>
<td>2.5 mm²</td>
<td>4.5 mm²</td>
<td>7.3 mm²</td>
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<td>Weight approx.: 1 mg</td>
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<td>Pitch: 0.5 mm</td>
<td>Weight: 16 mg</td>
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All products operate in the 1.7 to 5.5 V VCC range and -40 to +85 °C temperature range

Read more and get free samples at [http://www.st.com/standardeeprom](http://www.st.com/standardeeprom)